

## Thermal Gap Pad EU-TP200



### SPECIFIC PRODUCT CHARACTERISTICS:

Features&Benefits	Configurations	Typical application
<ul style="list-style-type: none"> <li>• Thermal Conductivity: 2.0 W/mK</li> <li>• High conformability</li> <li>• Electrically insulating</li> <li>• Naturally tacky</li> </ul>	<ul style="list-style-type: none"> <li>• Sheet 200x400mm</li> <li>• Custom Die-cut parts</li> <li>• Kiss cut parts on sheet</li> </ul>	<ul style="list-style-type: none"> <li>• Between electronic components such as Semiconductor, IC, CPU.MOS and heatsink.</li> <li>• Led Lighting, LCD TV, Telecom device, wireless Hub,NB, PC, power supply etc</li> <li>• Cooling Module, Thermal module, in all applications where a metal housing is used as heatsink.</li> </ul>

### CUSTOMIZATIONS:

Die Cutting	Water Jet Cut	Plotter Cut
		

**PRODUCT PROPERTIES:**

Properties	Units	Metric Value	Test Method
Construction & Composition	-	Silicone & Fiberglass	-
Color	-	Dark Gray	Visual
Thickness Range	mm	0,5~6,0	-
Hardness	Shore C	25	ASTM D2240
Density	g/cc	2,79	ASTM D792
Tensile Strength	KN/m	0,33	ASTM D412
Elongation	%	78%	ASTM D412
Continuous Use Temp	°C	-40 to 150	EN344
Breakdown Voltage	Kv/mm	≥ 6,0	ASTM D149
Volume Impedance	Ohm-cm	1,1*10 <sup>16</sup>	ASTM D257
Dielectric Constant	1MHz	5,75	ASTM D150
Flame Rating	-	V-0	UL94
Thermal Conductivity	W/mK	2,0	ASTM E1461
UL,RoHS, REACH	-	Compliance	-

Our customer are reminded that they bear the responsibility for testing Euro Technologies, Srl materials for their proposed use. Due to various application possibilities and conditions which are beyond our control, customers should carry out their own tests to determine the suitability for individual applications.

We reserve the right to change technical specifications without notice and take no responsibility for errors and misprints.